



SOT638-3

plastic thermal enhanced thin quad flat package; 100 leads;
body 14 x 14 x 1 mm; exposed die pad

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HTQFP100
Package type industry code	HTQFP100
Package style descriptive code	HTQFP (thermal enhanced thin quad flat package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MS-026
Mounting method type	S (surface mount)
Issue date	8-4-2008

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		13.9	-	14	14.1	mm
E	package width		13.9	-	14	14.1	mm
A	seated height		0.95	-	1	1.2	mm
A ₂	package height		0.95	-	1	1.05	mm
e	nominal pitch		-	-	0.5	-	mm
n ₂	actual quantity of termination		-	-	100	-	

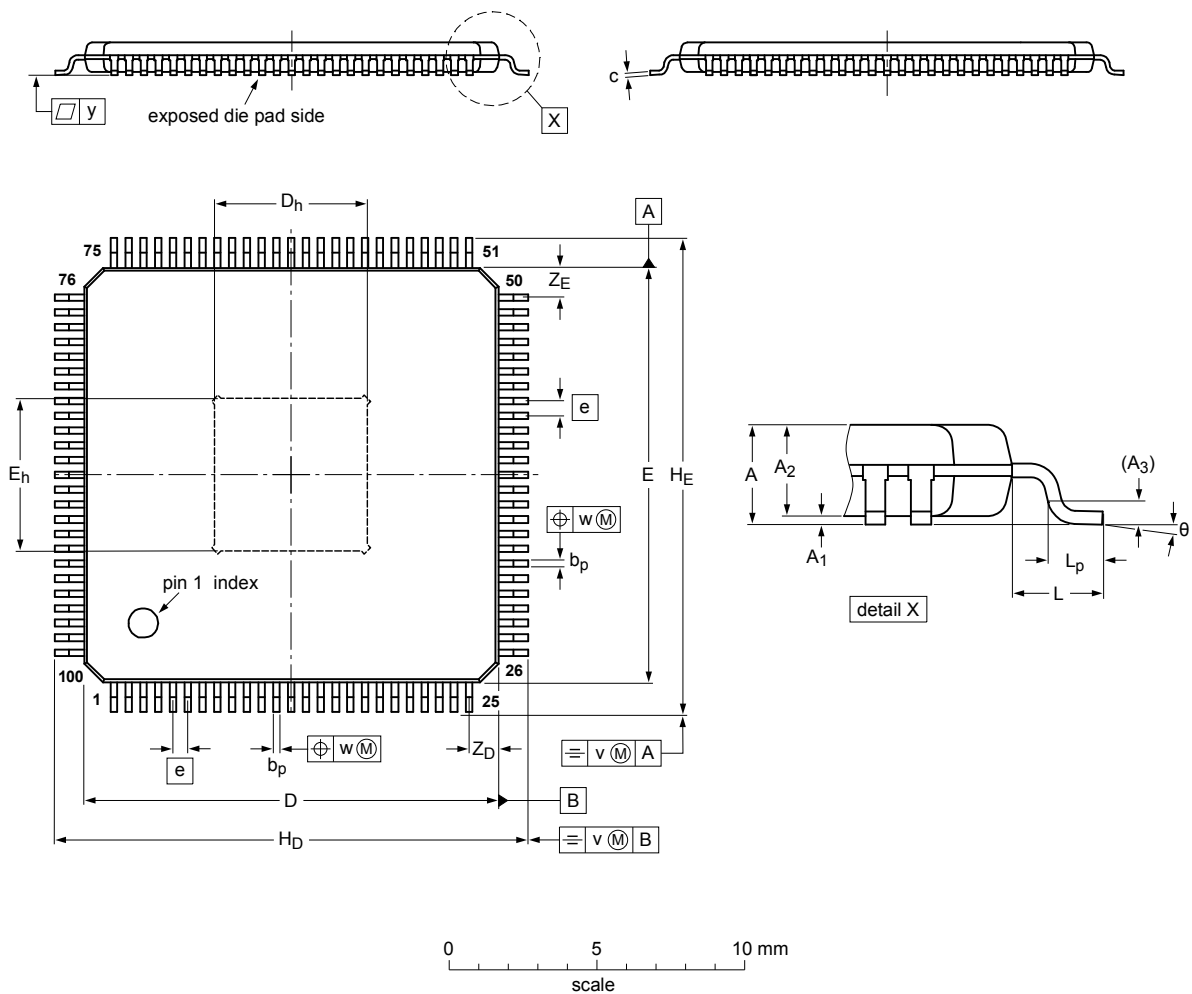


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2. Package outline

HTQFP100: plastic thermal enhanced thin quad flat package; 100 leads;
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DIMENSIONS (mm are the original dimensions)																						
UNIT		A	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	D _h	E ⁽¹⁾	E _h	e	H _D	H _E	L	L _p	v	w	y	Z _D ⁽¹⁾	Z _E ⁽¹⁾	θ
mm	max	1.20	0.15	1.05	0.25	0.27	0.20	14.1	5.7	14.1	5.7	0.5	16.15	16.15	1	0.75	0.2	0.08	0.08	1.15	1.15	7°
	nom	1.00	0.10	1.00		0.22	0.15	14.0	5.2	14.0	5.2		16.00	16.00		0.60				1.00	1.00	0°
	min	0.95	0.05	0.95		0.17	0.09	13.9	4.7	13.9	4.7		15.85	15.85		0.45				0.85	0.85	

Note
1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT638-3		MS-026				08-03-06 08-04-08

Fig. 1. Package outline HTQFP100 (SOT638-3)

3. Soldering

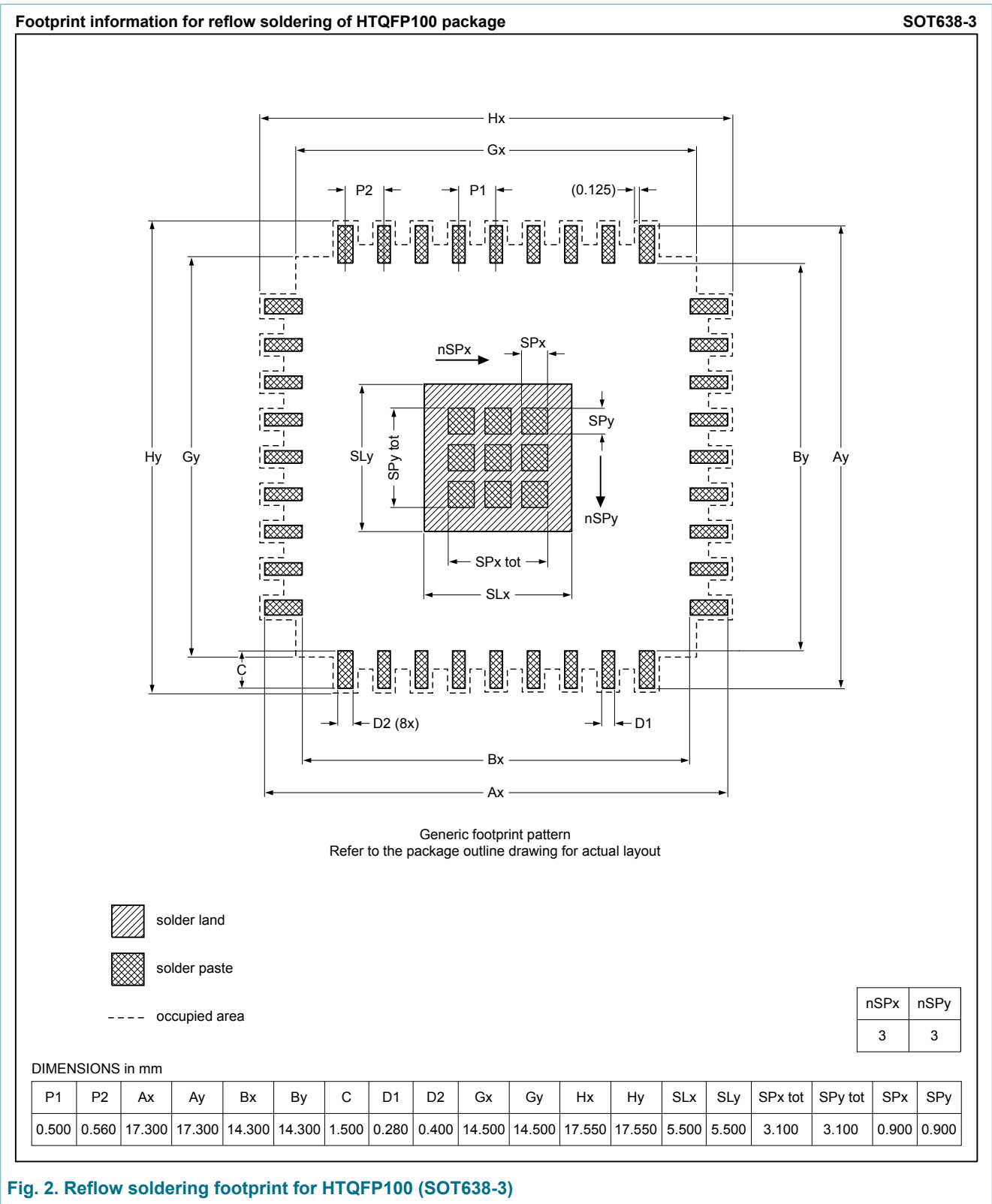


Fig. 2. Reflow soldering footprint for HTQFP100 (SOT638-3)

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4. Legal information

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